

DATA SHEET

GENERAL PURPOSE CHIP RESISTORS RC0201 (Pb Free) 5%, 1%





<u>SCOPE</u>

This specification describes RC0201 series chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

RC0201 X X X XX XXXX L

(1) (2) (3) (4) (5) (6)

(I) TOLERANCE

 $F = \pm 1\%$ | = ±5%

(2) PACKAGING TYPE

R = Paper/PE taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(4) TAPING REEL

- 07 = 7 inch dia. Reel
- 10 = 10 inch dia. Reel (not preferred)
- 13 = 13 inch dia. Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 56K, 1M, D1 ⁽¹⁾ .

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

NOTE

I. For dummy value.

ORDERING EXAMPLE

The ordering code of a RC0201 chip resistor, value 56 Ω with ±1% tolerance, supplied in 7-inch tape reel is: RC0201FR-0756RL.

NOTE

- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- 2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- 3. Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)

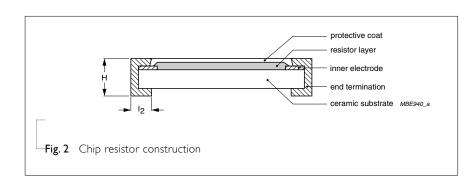






CONSTRUCTION

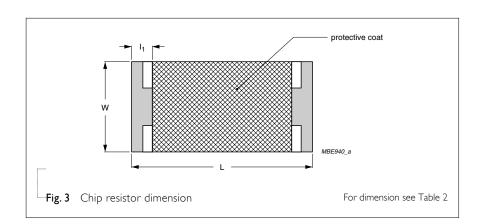
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat.



Finally, the two external terminations (pure Tin) are added. See fig. 2.

DIMENSIONS

Table 2	
ТҮРЕ	RC0201
L (mm)	0.60 ±0.03
W (mm)	0.30 ±0.03
H (mm)	0.23 ±0.03
lı (mm)	0.13 ±0.08
l ₂ (mm)	0.15 ±0.08





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ELECTRICAL CHARACTERISTICS

Table 3	
CHARACTERISTICS	RC0201 1/20 W
Operating Temperature Range	−55 °C to +125 °C
Maximum Working Voltage	15 V
Maximum Overload Voltage	50 V
Dielectric Withstanding Voltage	50 V
	5% (E24) Ι Ω to Ι ΜΩ
Resistance Range	1% (E96) Ι Ω to Ι ΜΩ
	Zero Ohm Jumper < 0.05 Ω
Temperature Coefficient	$10 \ \Omega < R \le 1 \ M\Omega $ ±250 ppm/°C
Temperature Coencient	$I \Omega < R \le I0 \Omega$ $-I00/+600 \text{ ppm/°C}$
Jumper Criteria	Rated Current 0.5 A
	Maximum Current I.0 A

FOOTPRINT AND SOLDERING <u>PROFILES</u>

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

PACKING STYLE AND PACKAGING QUANTITY

Table 4 Packing style and packaging quantity					
PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL		
RC0201	Paper / PE Taping Reel (R)	7" (178 mm)	10,000 units		
		10" (254 mm) / not preferred	20,000 units		
		I 3" (330 mm)	50,000 units		

NOTE

1. For Paper/PE tape and reel specification/dimensions, please see the special data sheet "Packing" document.





Chip Resistor Surface MountRCSERIES0201 (Pb Free)

FUNCTIONAL DESCRIPTION

POWER RATING

RC0201 rated power at 70°C is 1/20 W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

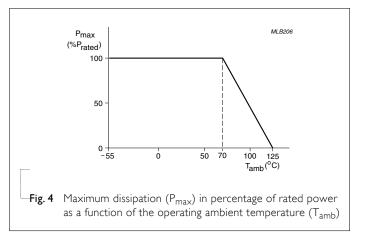
 $V=\sqrt{(P \times R)}$

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)





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TESTS AND REQUIREMENTS

EST	T TEST METHOD PROCEDURE		REQUIREMENTS		
Temperature	MIL-STD-202F-method 304; At +25/–55 °C and +25/+125 °C		Refer to table 3		
Coefficient of Resistance	JIS C 5202-4.8	Formula:			
(T.C.R.)					
()		T.C.R= $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$			
		Where t ₁ =+25 °C or specified room temperature			
		$t_2 = -55$ °C or +125 °C test temperature			
		R_1 =resistance at reference temperature in ohms			
		R_2 =resistance at test temperature in ohms			
Thermal Shock	MIL-STD-202F-method 107G;	At65 (+0/-10) °C for 2 minutes and at +125	±(0.5%+0.05 Ω) for 1% tol.		
	IEC 60115-1 4.19	(+10/-0) °C for 2 minutes; 25 cycles	\pm (1.0%+0.05 Ω) for 5% tol.		
Low	MIL-R-55342D-Para 4.7.4	At –65 (+0/–5) °C for I hour, RCWV applied	$\pm(0.5\%{+}0.05~\Omega)$ for 1% tol		
Temperature Operation		for 45 (+5/–0) minutes	$\pm (1.0\% {+} 0.05~\Omega)$ for 5% tol.		
Operation			No visible damage		
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	±(1.0%+0.05 Ω) for 1% tol.		
Overload	IEC 60115-1 4.13	temperature	±(2.0%+0.05 Ω) for 5% tol.		
			No visible damage		
Insulation	MIL-STD-202F-method 302;	RCOV for 1 minute	≥10 GΩ		
Resistance	IEC 60115-1 4.6.1.1	Type RC0201			
		Voltage (DC) 50 V			
Dielectric	MIL-STD-202F-method 301;	Maximum voltage (V _{rms}) applied for 1 minute	No breakdown or flashover		
Withstand	IEC 60115-1 4.6.1.1	Type RC0201			
Voltage		Voltage (AC) 50 V _{rms}			
Resistance to	MIL-STD-202F-method 210C;	Unmounted chips; 260 \pm 5 °C for 10 \pm 1	±(0.5%+0.05 Ω) for 1% tol.		
Soldering	IEC 60115-1 4.18	seconds	±(1.0%+0.05 Ω) for 5% tol.		
Heat			No visible damage		
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	±(1%+0.05 Ω) for 1% tol.		
-	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	±(3%+0.05 Ω) for 5% tol.		

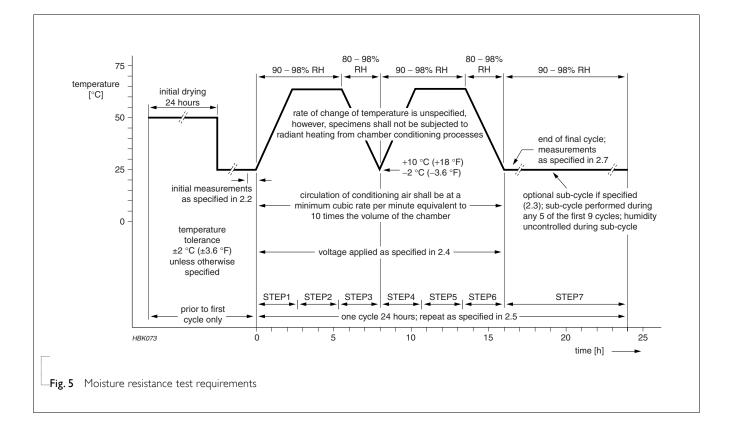
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ST	TEST METHOD	PROCEDURE	REQUIREMENTS			
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% cove	ered)		
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage			
Bending	JIS C 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	±(1.0%+0.05 Ω) for 1% tol.			
Strength	IEC 60115-1 4.15	resin PCB (FR4)	±(1.0%+0.05 Ω) for 5%	5 tol.		
		Bending: 5 mm	No visible damage			
Resistance to	MIL-STD-202F-method 215;	Isopropylalcohol (C ₃ H ₇ OH) or dichloromethane	No smeared			
Solvent	IEC 60115-1 4.29	(CH_2CI_2) followed by brushing				
Noise	JIS C 5202 5.9;	Maximum voltage (V _{ms}) applied.	Resistors range	Value		
	IEC 60115-1 4.12		R < 100 Ω	10 df		
			$ 00 \ \Omega \le R < K\Omega$	20 dł		
			$ K\Omega \le R < 0 K\Omega$	30 dł		
			$10 \text{ K}\Omega \leq \text{R} < 100 \text{ K}\Omega$	40 dl		
			$100 \text{ K}\Omega \leq \text{R} < 1 \text{ M}\Omega$	46 dl		
			$ M\Omega \le R \le 22 M\Omega$	48 dl		
Humidity (steady state)	JIS C 5202 7.5; IEC 601 15-8 4.24.8	I,000 hours; 40±2 °C; 93(+2/–3)% RH RCWV applied for I.5 hours on and 0.5 hour off	$\pm (0.5\% + 0.05 \Omega)$ for 1% ±(2.0% + 0.05 Ω) for 5%	s tol.		
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5%	s tol.		
	IEC 60115-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C	±(0.5%+0.05 Ω) for 1%			
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5%	s tol.		
(steady state)	IEC 60115-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5%	5 tol. 5 tol.		
(steady state) Leaching	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5% No visible damage	5 tol. 5 tol.		
(steady state) Leaching Intermittent	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5% No visible damage ±(1.0%+0.05 Ω) for 1%	5 tol. 5 tol.		
(steady state) Leaching Intermittent Overload Resistance to	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	±(0.5%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5% No visible damage ±(1.0%+0.05 Ω) for 1%	5 tol. 5 tol. 5 tol. 5 tol.		
(steady state) Leaching Intermittent Overload Resistance to Vibration	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8 On request	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles On request	\pm (0.5%+0.05 Ω) for 1% \pm (2.0%+0.05 Ω) for 5% No visible damage \pm (1.0%+0.05 Ω) for 1% \pm (2.0%+0.05 Ω) for 5%	5 tol. 5 tol. 5 tol. 5 tol. 5 tol.		



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 Chip Resistor Surface Mount
 RC
 SERIES
 0201 (Pb Free)

<u>REVISION HISTORY</u>

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Sep 03, 2004	-	- Test method and procedure updated
			- PE tape added (paper tape will be replaced by PE tape)

